

# PBSS4021SP

20 V, 6.3 A PNP/PNP low  $V_{CEsat}$  (BISS) transistor

Rev. 2 — 11 October 2010

Product data sheet

## 1. Product profile

### 1.1 General description

PNP/PNP low  $V_{CEsat}$  Breakthrough In Small Signal (BISS) transistor in a SOT96-1 (SO8) medium power Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

Type number	Package		NPN/PNP complement	NPN/PNP complement
	NXP	Name		
PBSS4021SP	SOT96-1	SO8	PBSS4021SN	PBSS4021SPN

### 1.2 Features and benefits

- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability  $I_C$  and  $I_{CM}$
- High collector current gain ( $h_{FE}$ ) at high  $I_C$
- High efficiency due to less heat generation
- Smaller required Printed-Circuit Board (PCB) area than for conventional transistors

### 1.3 Applications

- Loadswitch
- Battery-driven devices
- Power management
- Charging circuits
- Power switches (e.g. motors, fans)

### 1.4 Quick reference data

Table 2. Quick reference data

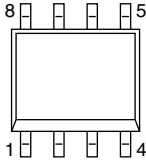
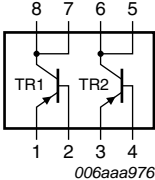
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	-20	V
$I_C$	collector current		-	-	-6.3	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	-15	A
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = -5$ A; $I_B = -0.5$ A <a href="#">[1]</a>	-	36	54	m $\Omega$

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .



## 2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	emitter TR1		 006aaa976
2	base TR1		
3	emitter TR2		
4	base TR2		
5	collector TR2		
6	collector TR2		
7	collector TR1		
8	collector TR1		

## 3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PBSS4021SP	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1

## 4. Marking

Table 5. Marking codes

Type number	Marking code
PBSS4021SP	4021SP

## 5. Limiting values

Table 6. Limiting values

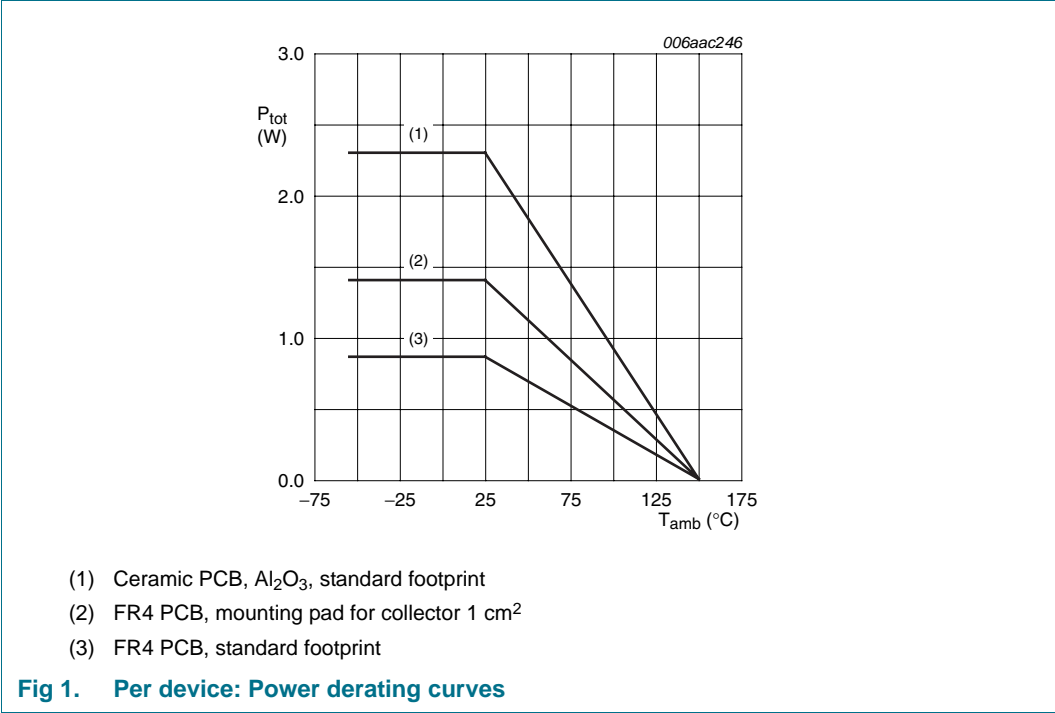
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per transistor					
V <sub>CBO</sub>	collector-base voltage	open emitter	-	−20	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	−20	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	−5	V
I <sub>C</sub>	collector current		-	−6.3	A
I <sub>CM</sub>	peak collector current	single pulse; t <sub>p</sub> ≤ 1 ms	-	−15	A
I <sub>B</sub>	base current		-	−1	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1] -	0.73	W
			[2] -	1	W
			[3] -	1.7	W

**Table 6. Limiting values ...continued**  
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per device</b>					
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1] -	0.86	W
			[2] -	1.4	W
			[3] -	2.3	W
T <sub>j</sub>	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-55	+150	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.  
[3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

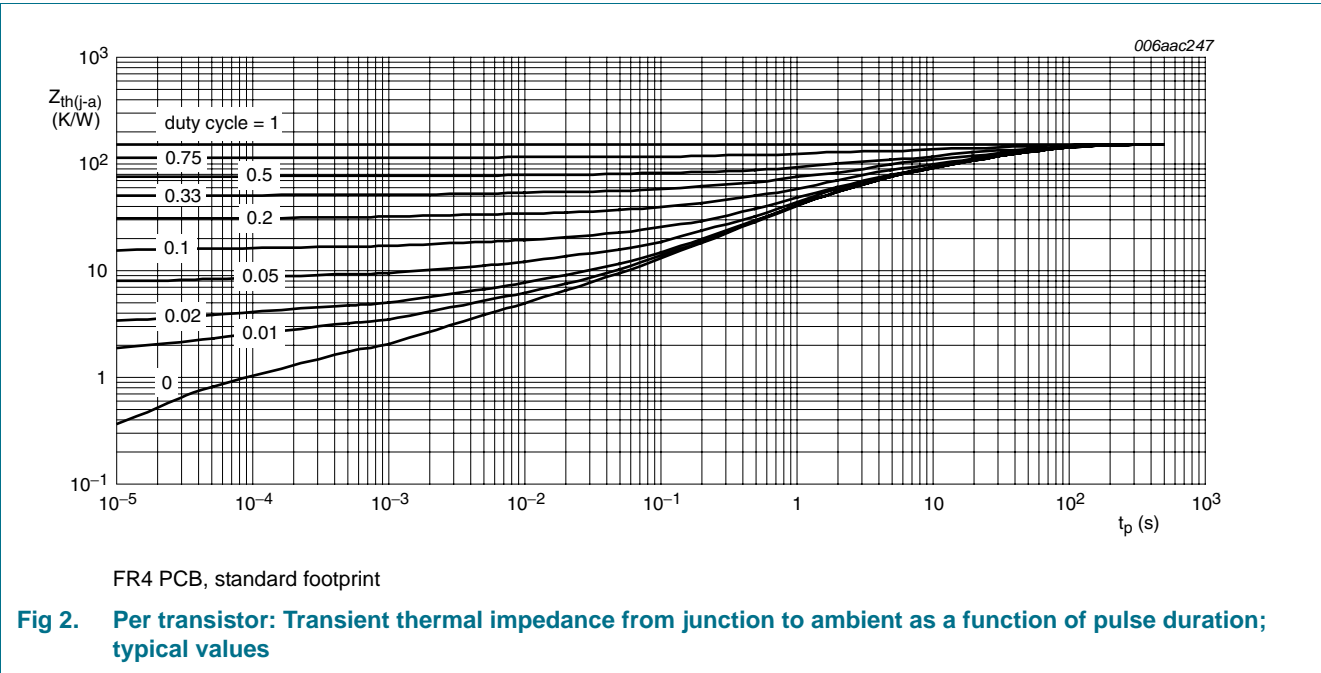


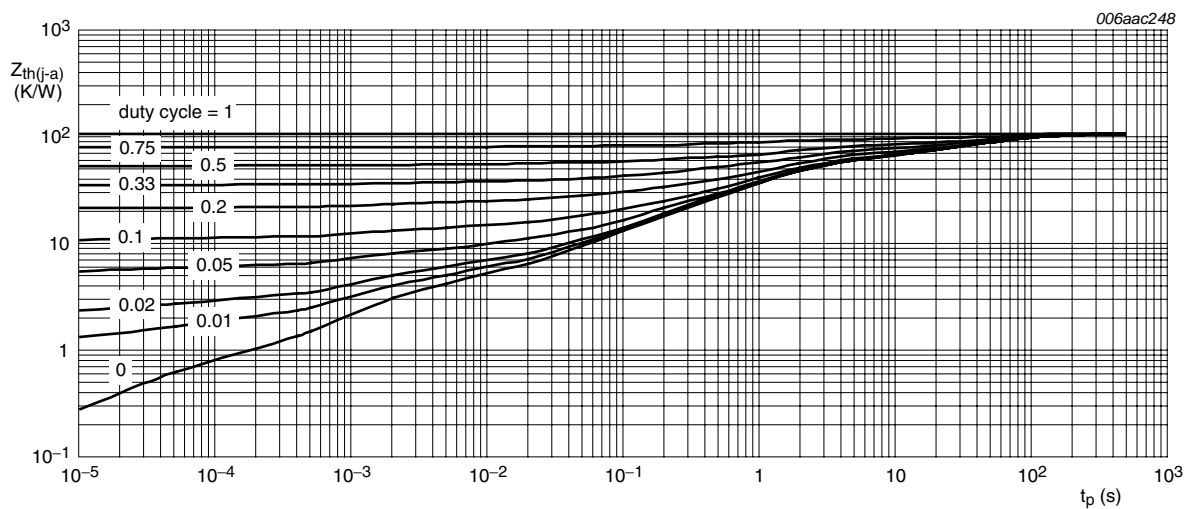
6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1] -	-	170	K/W
			[2] -	-	125	K/W
			[3] -	-	75	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		-	-	40	K/W
Per device						
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1] -	-	145	K/W
			[2] -	-	90	K/W
			[3] -	-	55	K/W

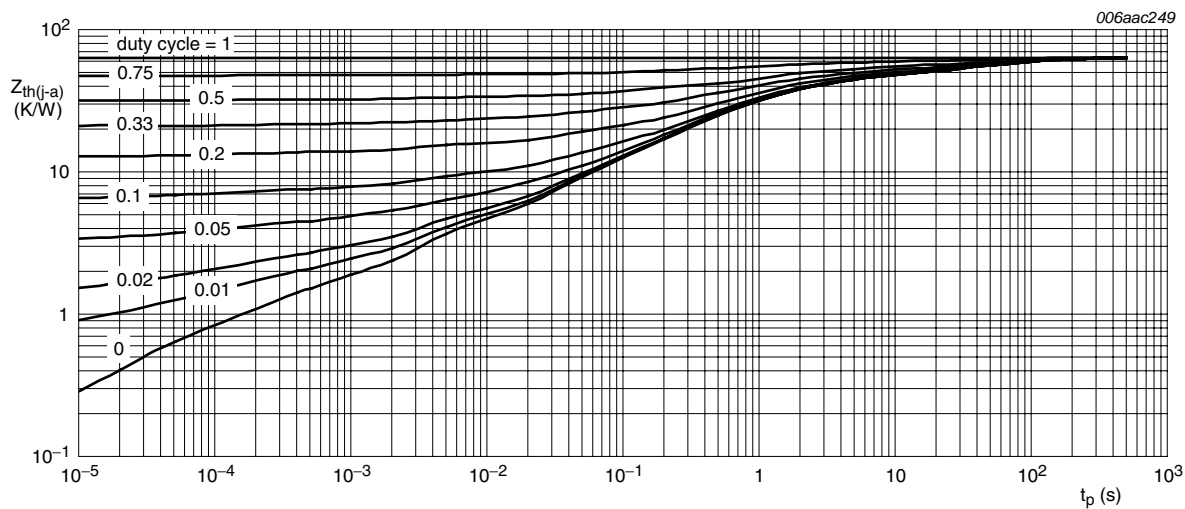
- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.
- [3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.





FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>

Fig 3. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Fig 4. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

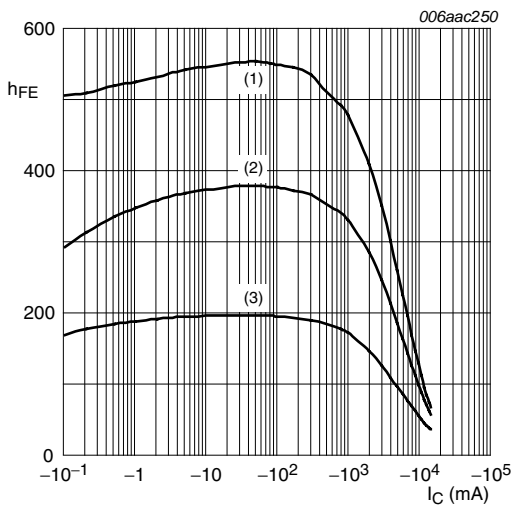
## 7. Characteristics

**Table 8. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

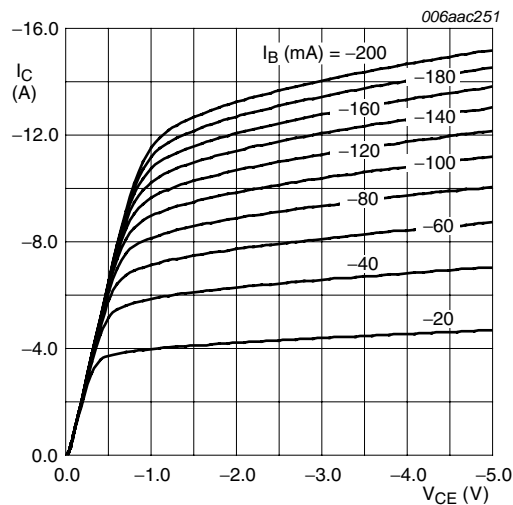
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Per transistor							
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = −20 V; I <sub>E</sub> = 0 A	-	-	−100	nA	
		V <sub>CB</sub> = −20 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	−50	μA	
I <sub>CES</sub>	collector-emitter cut-off current	V <sub>CE</sub> = −16 V; V <sub>BE</sub> = 0 V	-	-	−100	nA	
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = −5 V; I <sub>C</sub> = 0 A	-	-	−100	nA	
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = −2 V	[1]				
		I <sub>C</sub> = −500 mA	250	400	-		
		I <sub>C</sub> = −1 A	250	400	-		
		I <sub>C</sub> = −2 A	200	350	-		
		I <sub>C</sub> = −4 A	150	300	-		
		I <sub>C</sub> = −7 A	80	200	-		
V <sub>CEsat</sub>	collector-emitter saturation voltage		[1]				
		I <sub>C</sub> = −1 A; I <sub>B</sub> = −50 mA	-	−45	−68	mV	
		I <sub>C</sub> = −1 A; I <sub>B</sub> = −10 mA	-	−70	−115	mV	
		I <sub>C</sub> = −2 A; I <sub>B</sub> = −40 mA	-	−100	−150	mV	
		I <sub>C</sub> = −4 A; I <sub>B</sub> = −200 mA	-	−150	−225	mV	
		I <sub>C</sub> = −4 A; I <sub>B</sub> = −40 mA	-	−250	−375	mV	
	I <sub>C</sub> = −6.5 A; I <sub>B</sub> = −325 mA	-	−235	−350	mV		
R <sub>CEsat</sub>	collector-emitter saturation resistance	I <sub>C</sub> = −5 A; I <sub>B</sub> = −500 mA	[1]	-	36	54	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage		[1]				
		I <sub>C</sub> = −1 A; I <sub>B</sub> = −100 mA	-	−0.85	−1	V	
		I <sub>C</sub> = −4 A; I <sub>B</sub> = −400 mA	-	−1	−1.2	V	
V <sub>BEon</sub>	base-emitter turn-on voltage	V <sub>CE</sub> = −2 V; I <sub>C</sub> = −2 A	[1]	-	−0.76	−0.85	V
t <sub>d</sub>	delay time	V <sub>CC</sub> = −12.5 V; I <sub>C</sub> = −1 A;	-	40	-	ns	
t <sub>r</sub>	rise time	I <sub>Bon</sub> = −0.05 A; I <sub>Boff</sub> = 0.05 A	-	55	-	ns	
t <sub>on</sub>	turn-on time		-	95	-	ns	
t <sub>s</sub>	storage time		-	340	-	ns	
t <sub>f</sub>	fall time		-	85	-	ns	
t <sub>off</sub>	turn-off time		-	425	-	ns	
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = −10 V; I <sub>C</sub> = −100 mA; f = 100 MHz	-	105	-	MHz	
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = −10 V; I <sub>E</sub> = i <sub>e</sub> = 0 A; f = 1 MHz	-	95	-	pF	

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .



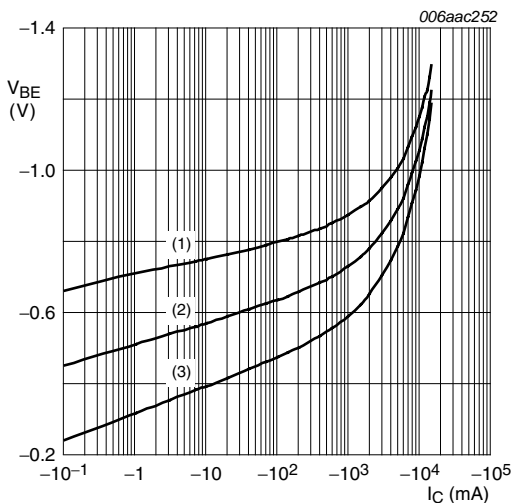
- $V_{CE} = -2$  V
- (1)  $T_{amb} = 100$  °C
  - (2)  $T_{amb} = 25$  °C
  - (3)  $T_{amb} = -55$  °C

Fig 5. DC current gain as a function of collector current; typical values



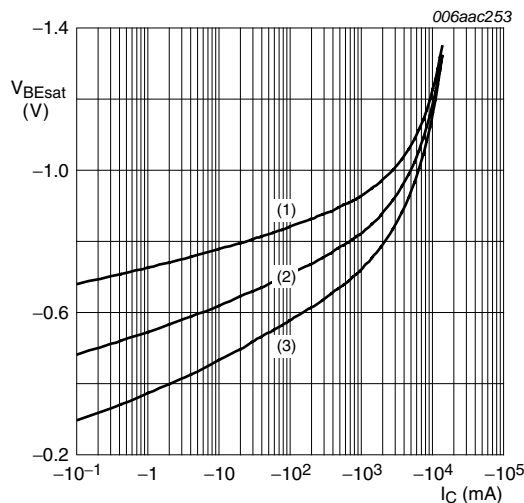
$T_{amb} = 25$  °C

Fig 6. Collector current as a function of collector-emitter voltage; typical values



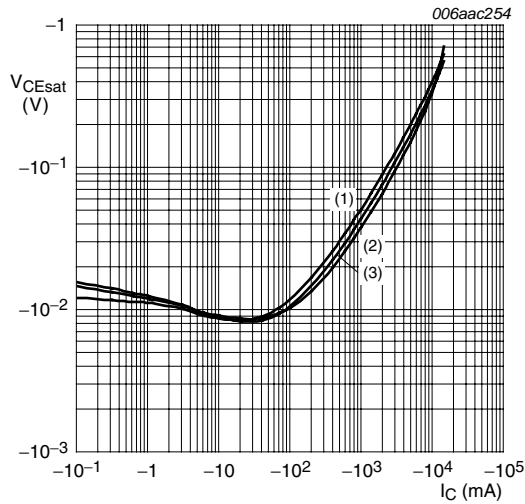
- $V_{CE} = -2$  V
- (1)  $T_{amb} = -55$  °C
  - (2)  $T_{amb} = 25$  °C
  - (3)  $T_{amb} = 100$  °C

Fig 7. Base-emitter voltage as a function of collector current; typical values



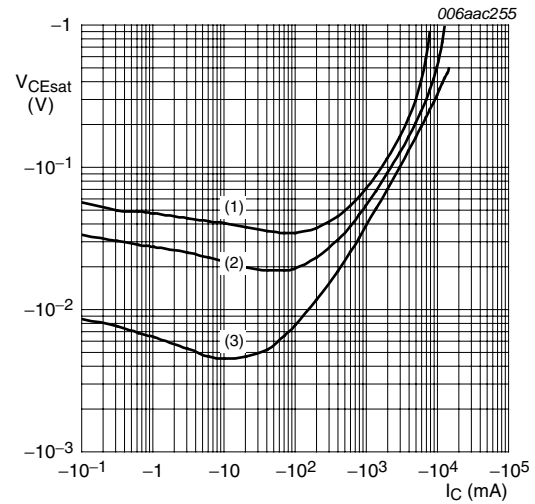
- $I_C/I_B = 20$
- (1)  $T_{amb} = -55$  °C
  - (2)  $T_{amb} = 25$  °C
  - (3)  $T_{amb} = 100$  °C

Fig 8. Base-emitter saturation voltage as a function of collector current; typical values



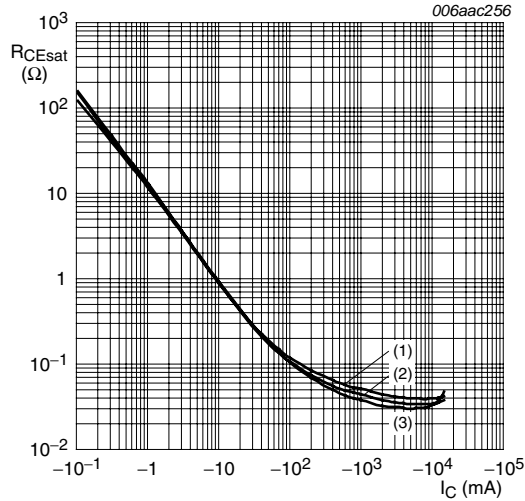
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 9. Collector-emitter saturation voltage as a function of collector current; typical values**



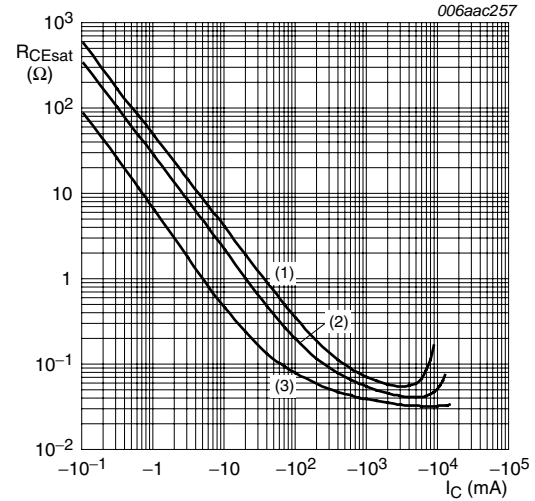
- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 10. Collector-emitter saturation voltage as a function of collector current; typical values**



- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 11. Collector-emitter saturation resistance as a function of collector current; typical values**



- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 12. Collector-emitter saturation resistance as a function of collector current; typical values**



8. Test information

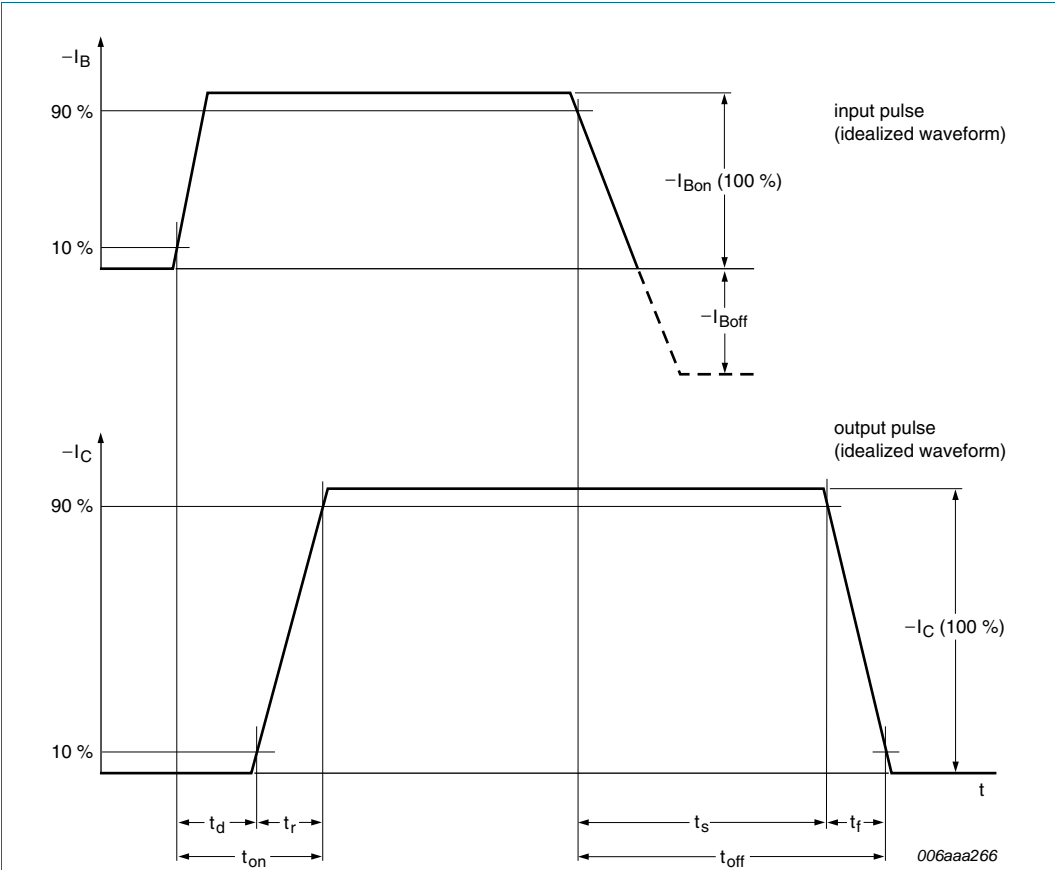
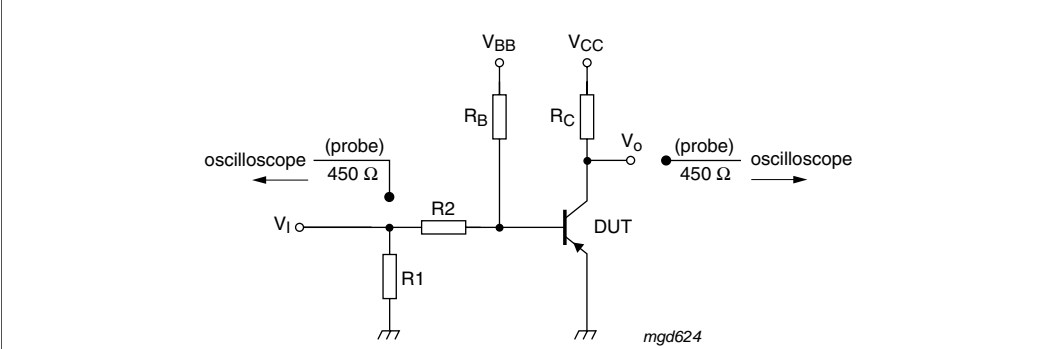


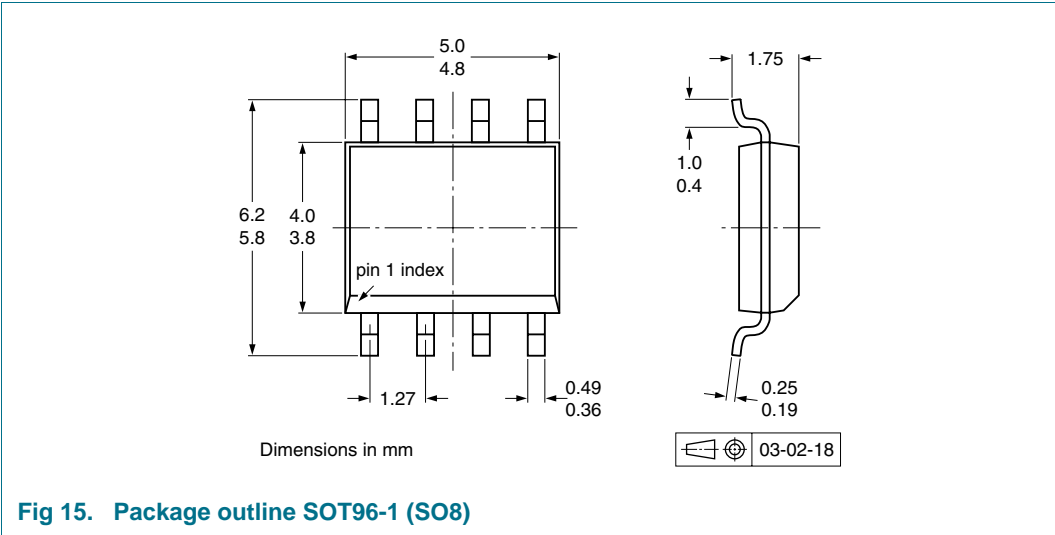
Fig 13. BISS transistor switching time definition



$V_{CC} = -12.5\text{ V}$ ;  $I_C = -1\text{ A}$ ;  $I_{Bon} = -0.05\text{ A}$ ;  $I_{Boff} = 0.05\text{ A}$

Fig 14. Test circuit for switching times

9. Package outline



10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			1000	2500
PBSS4021SP	SOT96-1	8 mm pitch, 12 mm tape and reel	-115	-118

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

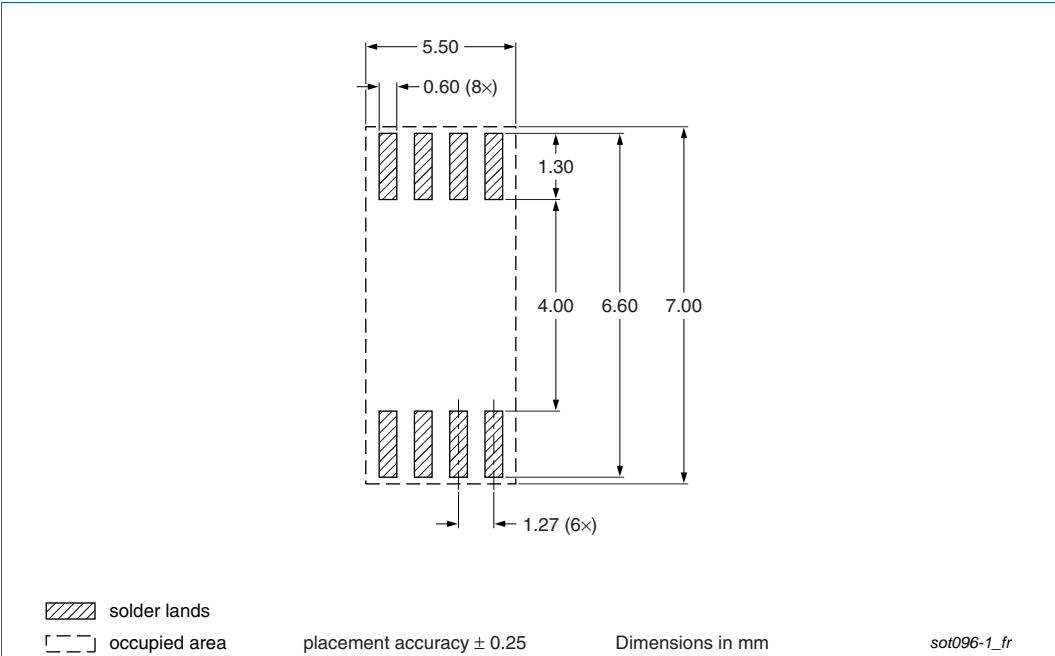


Fig 16. Reflow soldering footprint SOT96-1 (SO8)

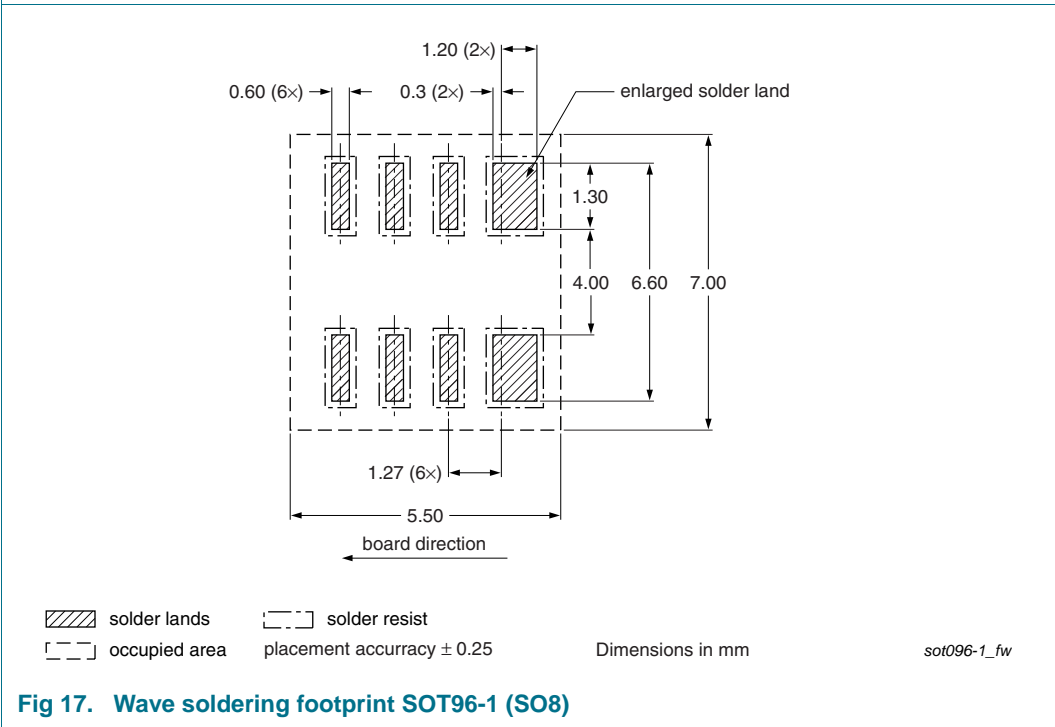


Fig 17. Wave soldering footprint SOT96-1 (SO8)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBSS4021SP v.2	20101011	Product data sheet	-	PBSS4021SP v.1
Modifications:	• <a href="#">Figure 1 “Per device: Power derating curves”</a> : updated.			
PBSS4021SP v.1	20100714	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## 15. Contents

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<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features and benefits . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Marking</b> . . . . .	<b>2</b>
<b>5</b>	<b>Limiting values</b> . . . . .	<b>2</b>
<b>6</b>	<b>Thermal characteristics</b> . . . . .	<b>4</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>6</b>
<b>8</b>	<b>Test information</b> . . . . .	<b>9</b>
<b>9</b>	<b>Package outline</b> . . . . .	<b>10</b>
<b>10</b>	<b>Packing information</b> . . . . .	<b>10</b>
<b>11</b>	<b>Soldering</b> . . . . .	<b>11</b>
<b>12</b>	<b>Revision history</b> . . . . .	<b>12</b>
<b>13</b>	<b>Legal information</b> . . . . .	<b>13</b>
13.1	Data sheet status . . . . .	13
13.2	Definitions . . . . .	13
13.3	Disclaimers . . . . .	13
13.4	Trademarks . . . . .	14
<b>14</b>	<b>Contact information</b> . . . . .	<b>14</b>
<b>15</b>	<b>Contents</b> . . . . .	<b>15</b>

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